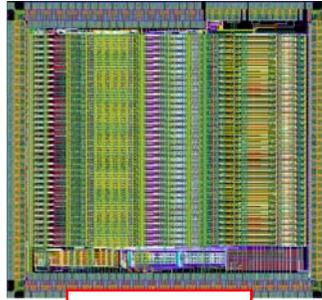
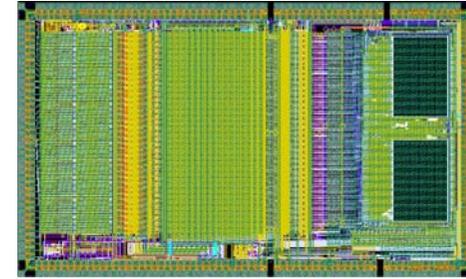


HaRDROC



SKIROC



SPIROC

EUDET JRA3 Front-End electronics in 2007



IN2P3
INSTITUT NATIONAL DE PHYSIQUE NUCLEAIRE
ET DE PHYSIQUE DES PARTICULES

C. de La Taille
IN2P3/LAL Orsay





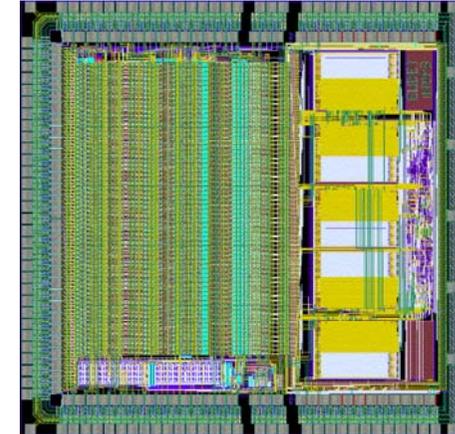
Tasks for CALICE/EUDET in 2007

- **Complete physics prototype**
 - Add and test DHCAL, complete physics program
 - Test effect of em shower on ASIC

- **Measure performance of 2nd generation ASIC**
 - On testbench in different labs
 - DHCAL ECAL, AHCAL
 - Test 2nd generation DAQ (UK)

- **Design Very Front-End boards with integrated ASICs**
 - DHCAL board with HARDROC
 - AHCAL board with SPIROC
 - ECAL board with SKIROC (or SPIROC)

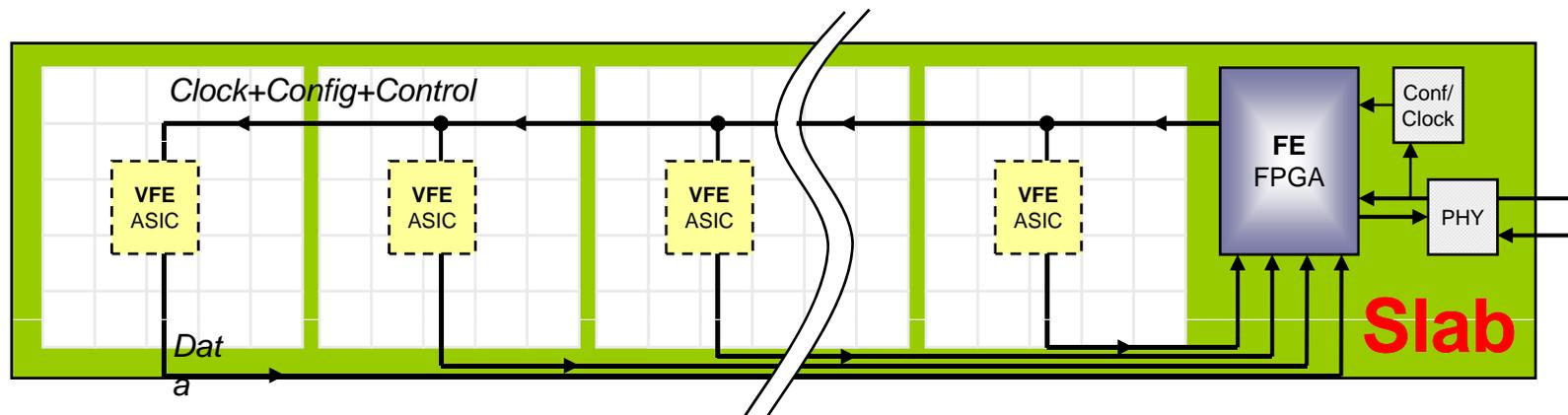
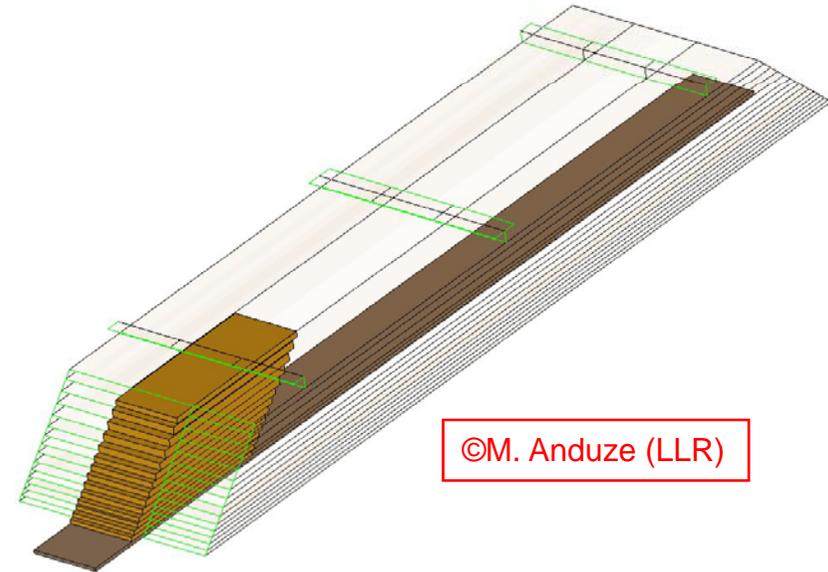
- **Design EUDET module(s) (demonstrator)**
 - Identify responsibilities and organize schedule
 - Moving to monthly meetings (in common with CALICE)
 - Aim at completing the design of EUDET modules beg 08





EUDET : ECAL module

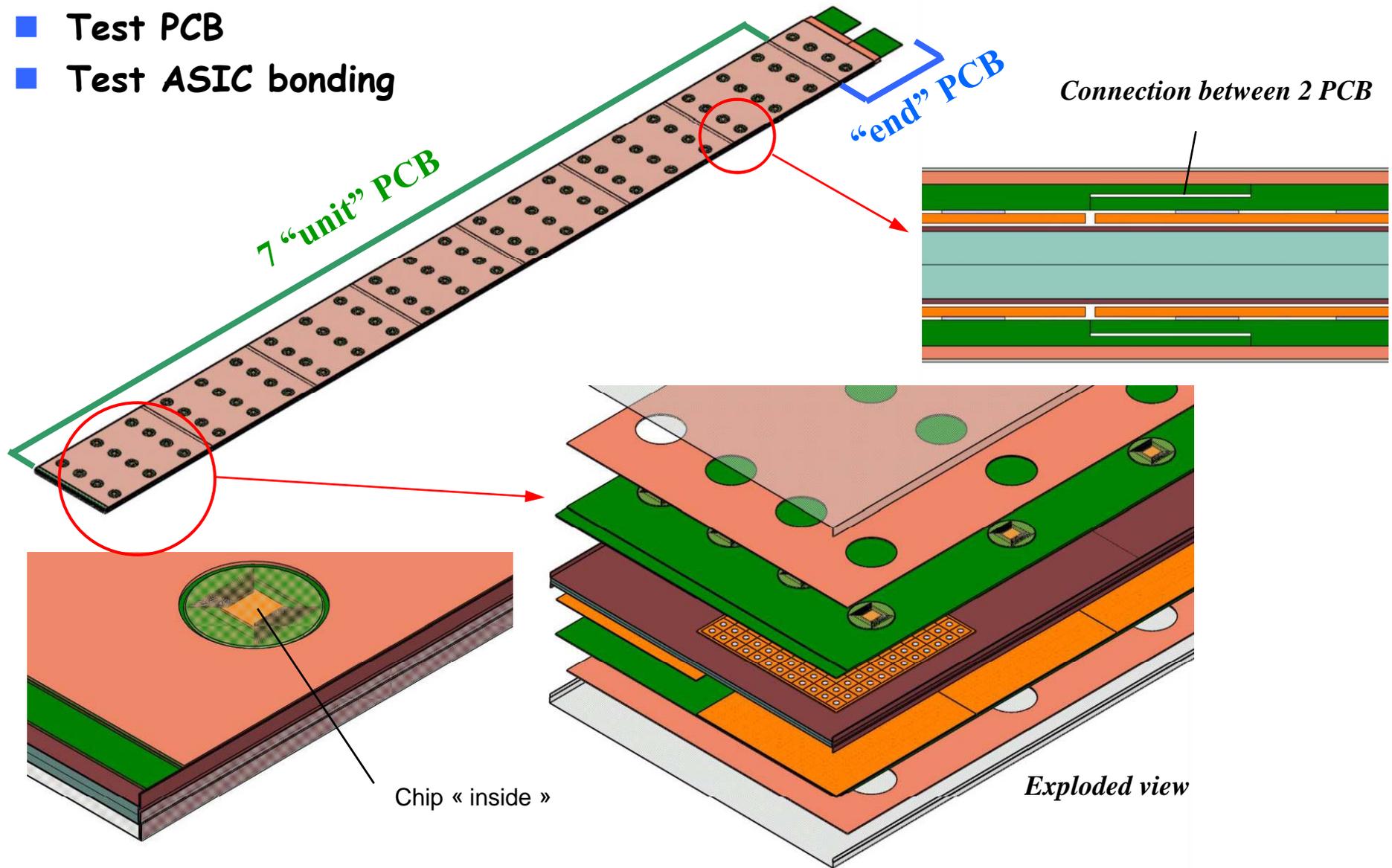
- **Electromagnetic calorimeter**
 - Prototype of a ($\sim 1/6$) module 0 : **one line & one column**
 - 150 cm long, 12 cm wide 30 layers
 - 1800 + 10800 channels
 - Test full scale mechanics + PCB
 - Can go in test beam
 - Test full integration + edge communications
- **To be delivered in 2009**





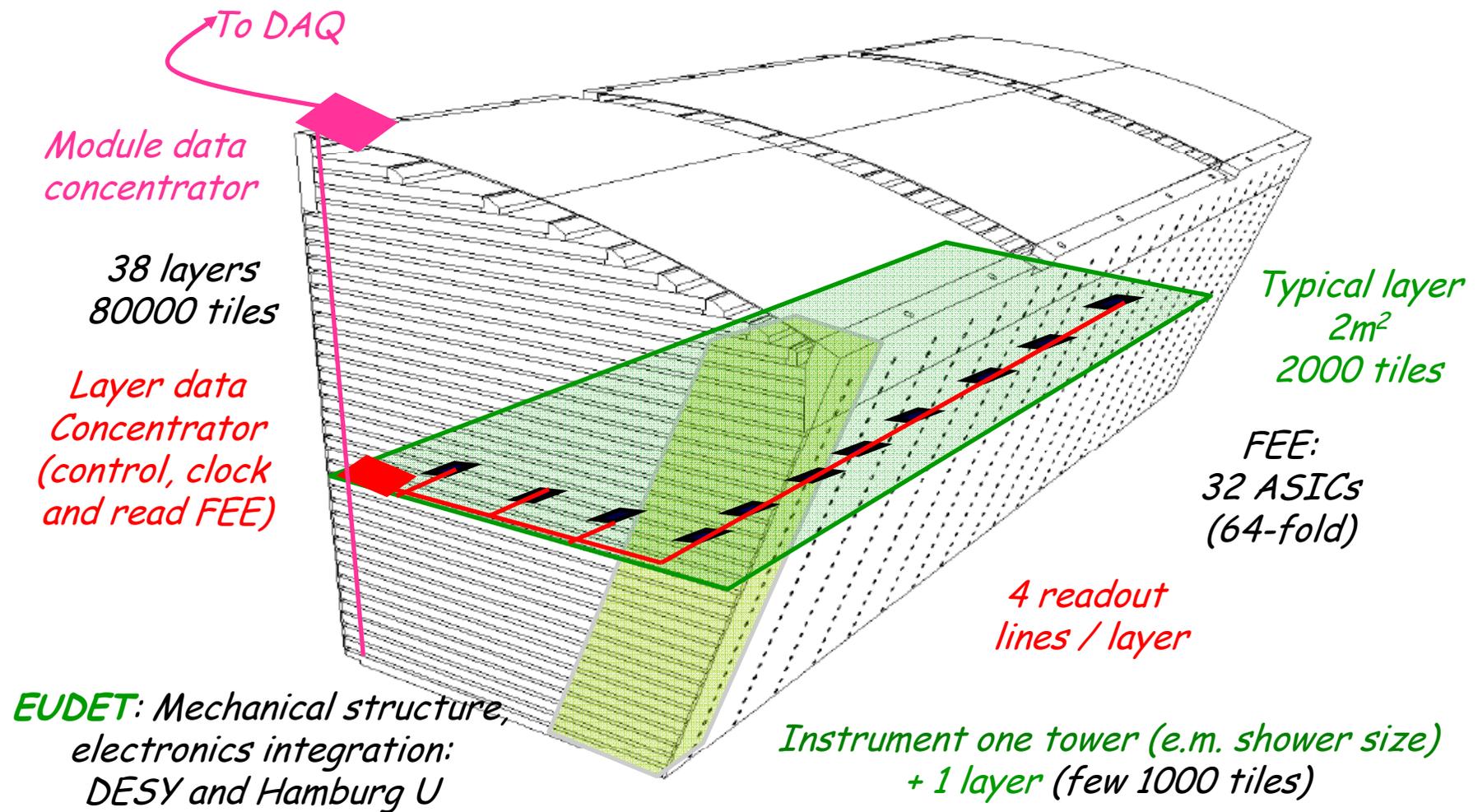
EUDET - Detector slab (2)

- Test PCB
- Test ASIC bonding





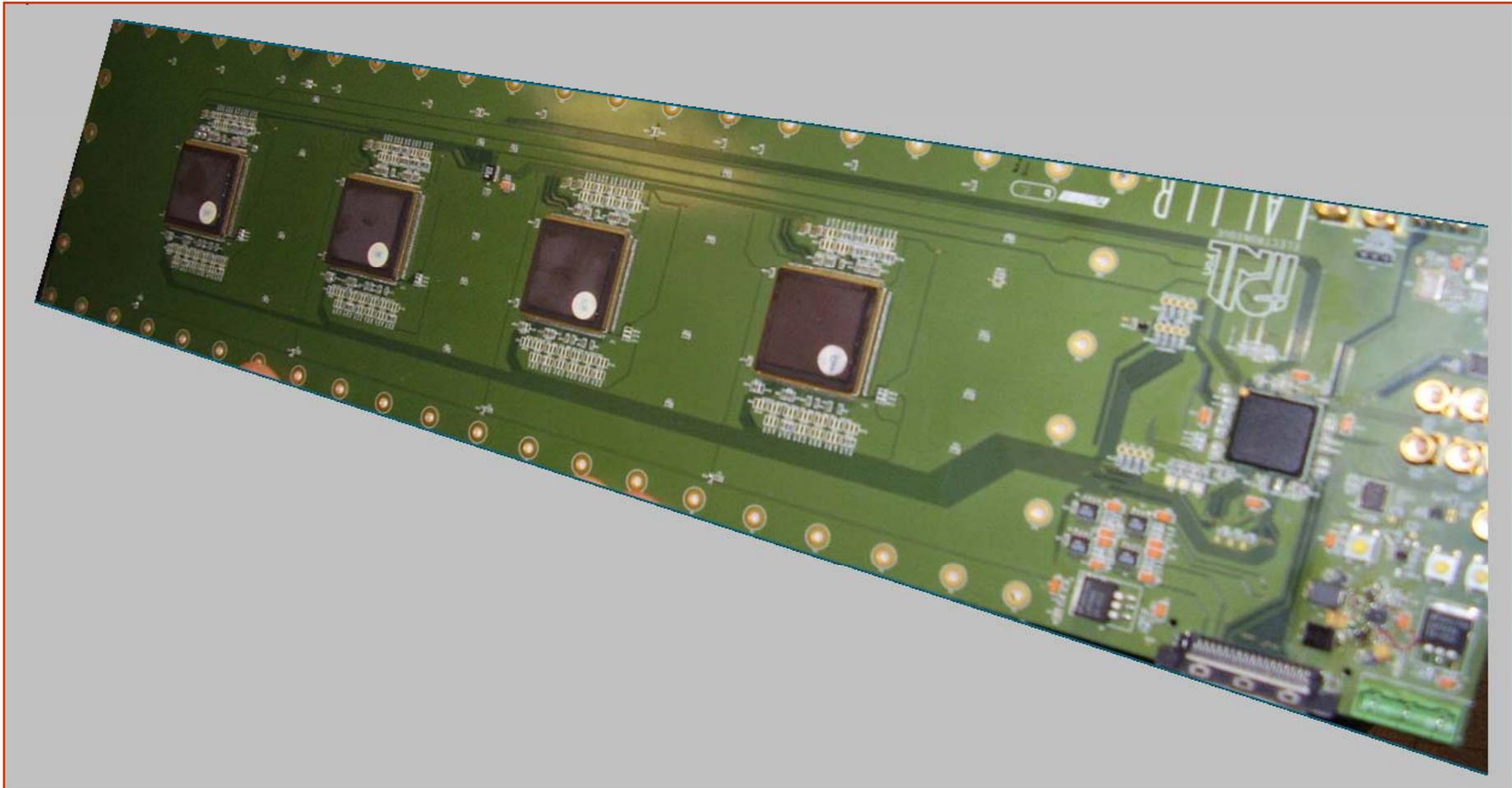
AHCAL architecture





DHCAL architecture

- First detector with 2nd generation ASCIs and 2nd generation DAQ
- Board received in june 07, tests starting

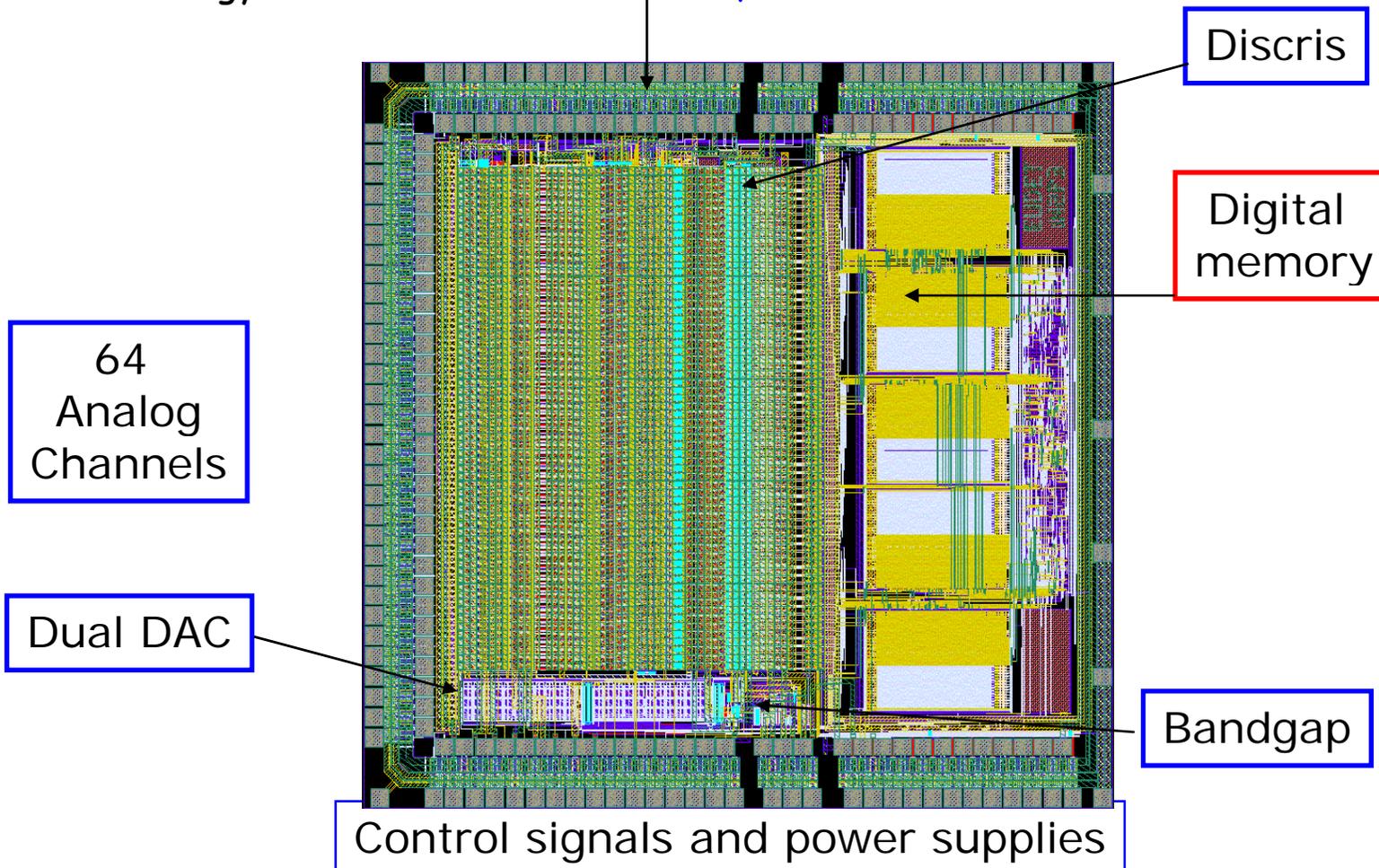




HaRDROC chip for DHCAL [LAL,IPNL]

JRA3
Milestone

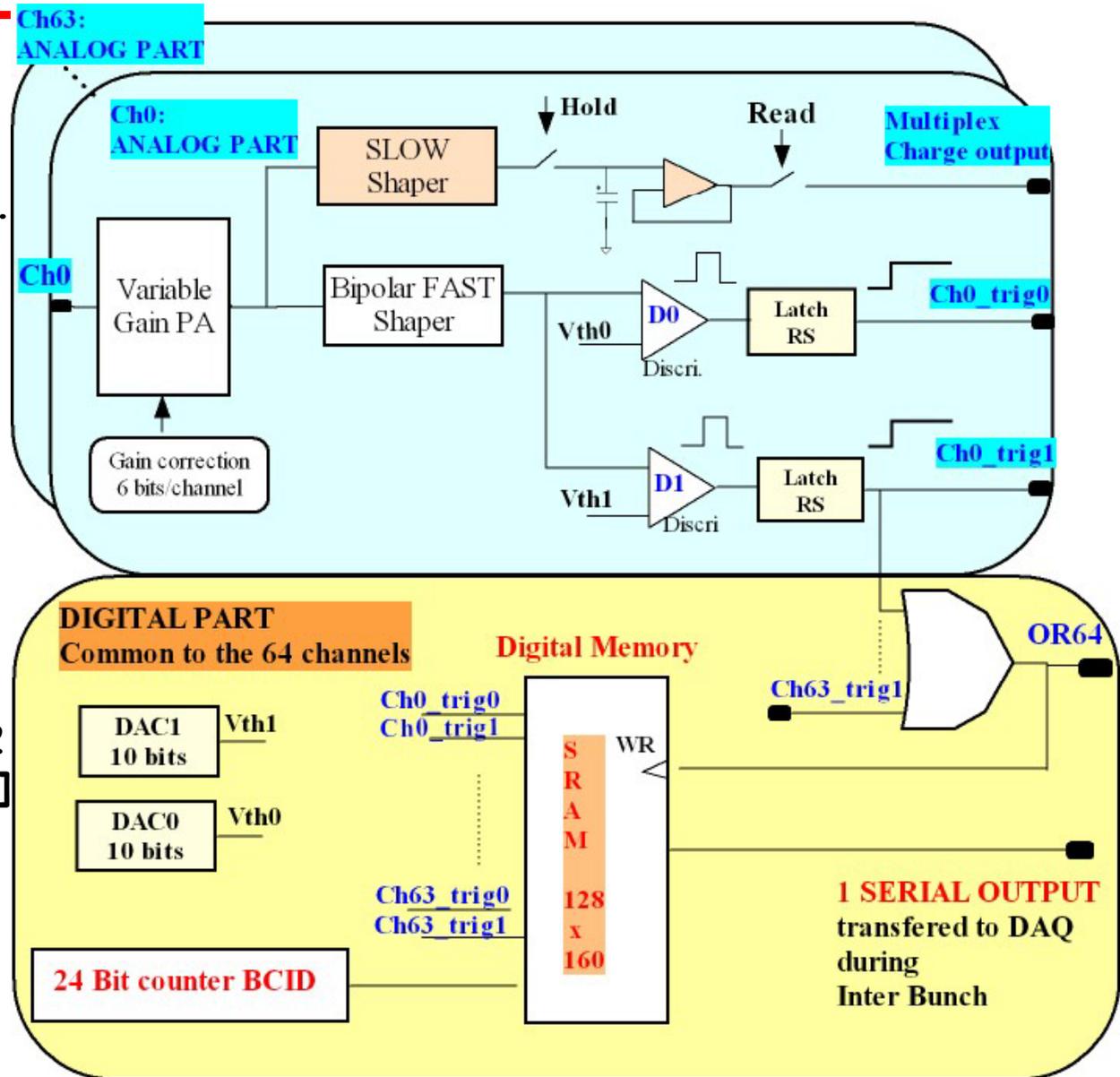
- **Hadronic Rpc Detector Read Out Chip (Sept 06)**
 - 64 inputs, preamp + shaper+ 2 discris + memory + **Full power pulsing**
 - Compatible with 1st and **2nd generation DAQ** : only 1 digital data output
 - Technology : **AMS SiGe BiCMOS 0.35 μm**





HaRDROC architecture

- Full power pulsing
- Digital memory: Data saved during bunch train.
- Only one serial output @ 1 or 5MHz
- Store all channels and BCID for every hit. Depth = 128 bits
- Data format : $128(\text{depth}) \times [2\text{bit} \times 64\text{ch} + 2\text{4bit}(\text{BCID}) + 8\text{bit}(\text{Header})] = 20\text{kbits}$
- Based on MAROC ASIC, but several design changes

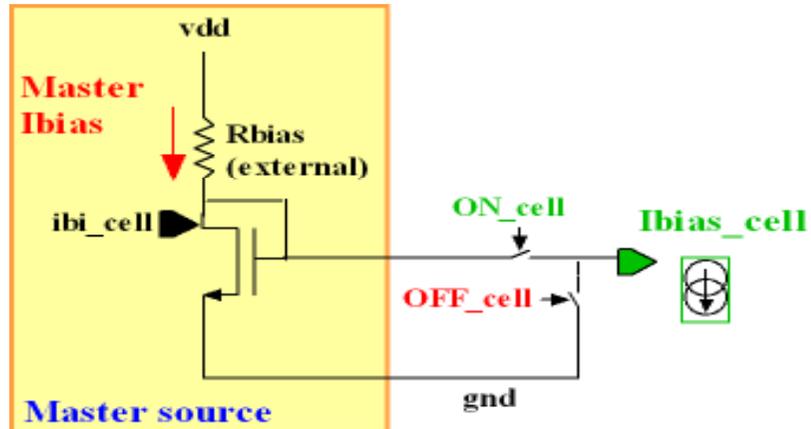




HARDROC POWER PULSING: Power dissipation (1)

Maximum power available:

- 10 μW / channel with 0.5% duty cycle
 $\Rightarrow 640\mu\text{W}/3.5\text{V} = \mathbf{180 \mu\text{A}}$ for the entire chip
- OFF**= Ibias _cell switched off during interbunch:



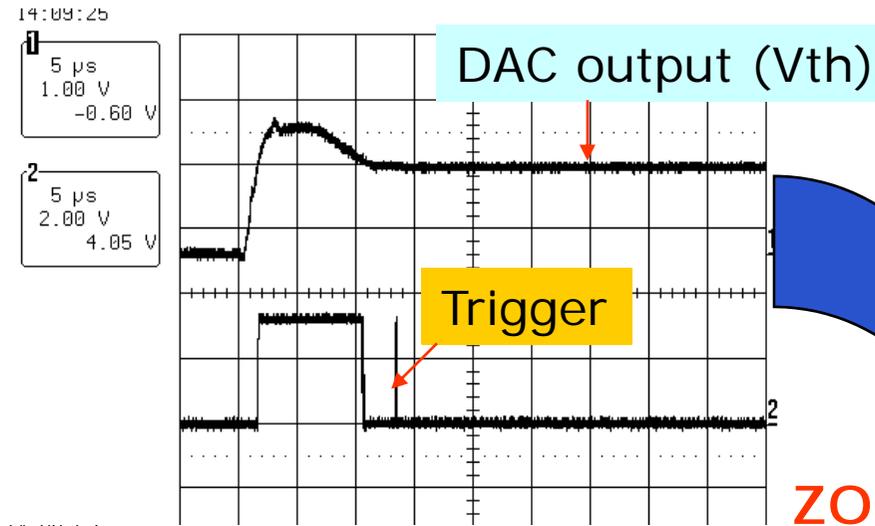
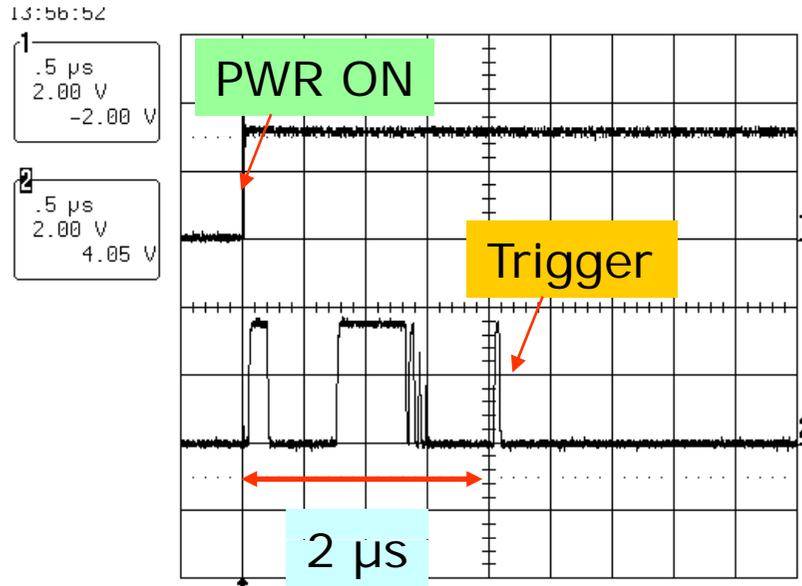
- BUT** a few forgotten switches...
 - Bandgap, some reference voltages not power pulsed
- Easy to fix in the production version**

	ON	OFF
Vdd_pad	0	
Vdd_pa	5.8 mA	5.6 μA
Vdd_fsb	4.9 mA	65 μA
Vdd_d0	2.8 mA	78 μA
Vdd_d1	2.7 mA	0
Vddd+ vddd2	3.3mA	200 μA + 0 (Clk OFF)
Vdd_dac	0.77 mA	218 μA
Vdd_bandgap	5.05 mA	2.73 mA
Total (noPP)	25.3 mA	3.2mA
Total with 0.5% PP	125 μA	0 hopefully

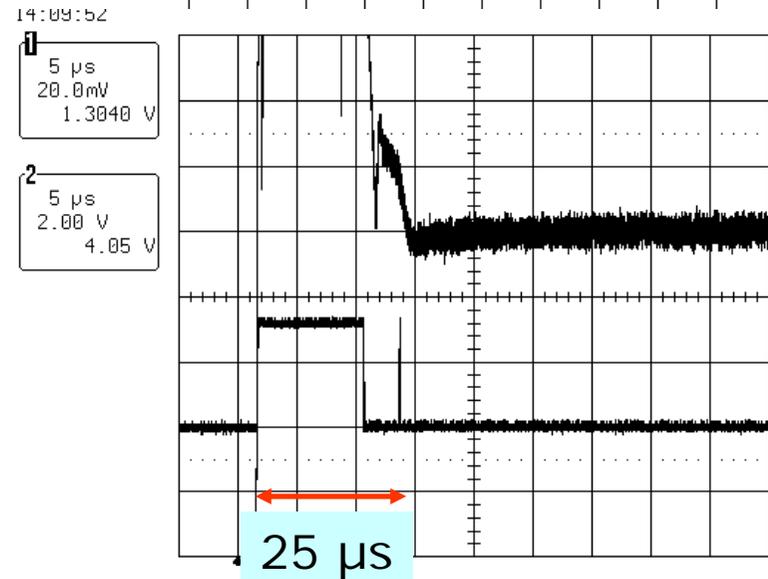
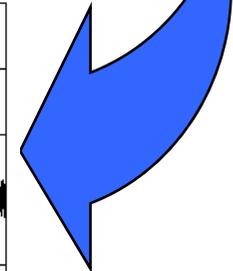
SW to be added to switch off all the master Ibias, Vref, V_BG...



HARDROC Power pulsing: « Awake » time (2)

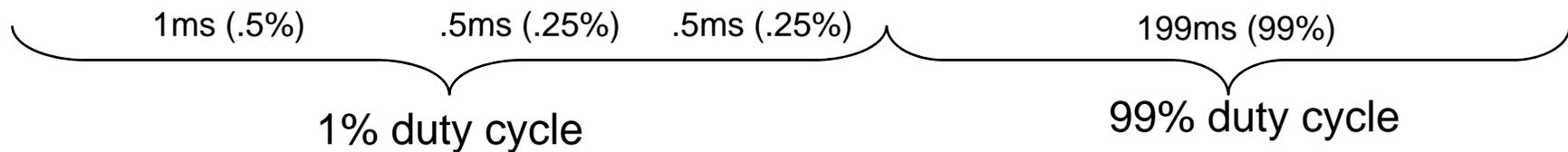
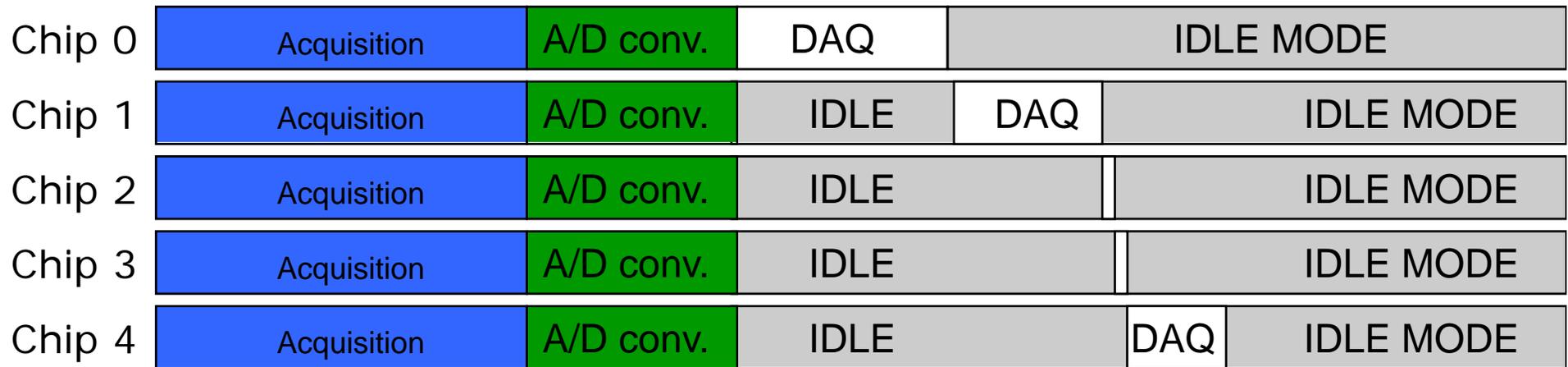
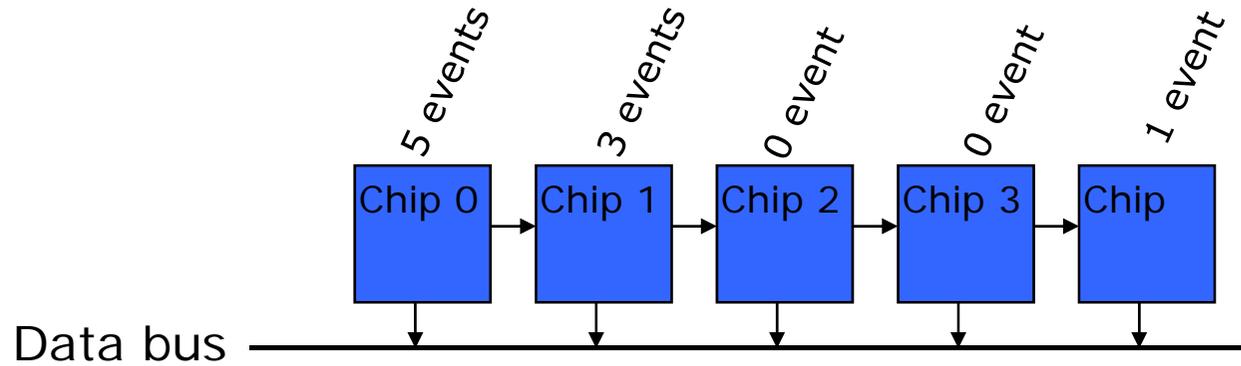


ZOOM



- PWR ON: ILC like (1ms,199ms)
- All decoupling capacitors removed
- PP of the analog part:
 - Input signal synchronised on PWR ON
 - Injection of 100fC, Threshold= 30fC
 - => Awake time= 2 μ s
- Power pulsing of the DAC:
 - 25 μ s (slew rate limited)

Read out : token ring



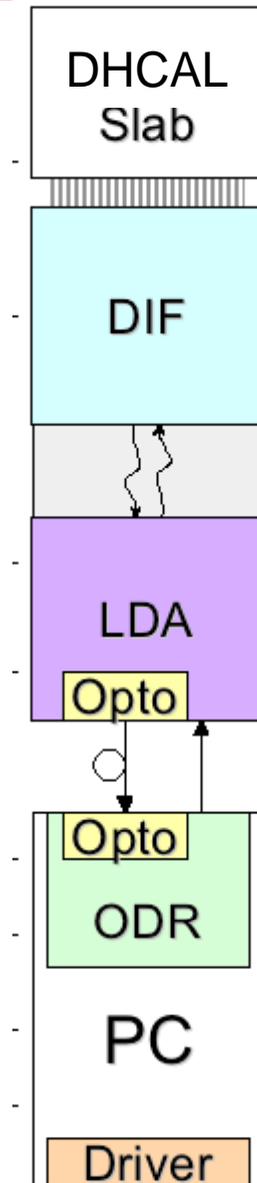
Digital part: DAQ2

■ DAQ and online system

- Common to all detectors
- Crateless, non-custom, **ILC-like system** with readout directly into PCs
- System-dependences isolated to **single interface** (LDA-DIF)
- DIF task force to define **interface** to slabs and DAQ

■ Offline software

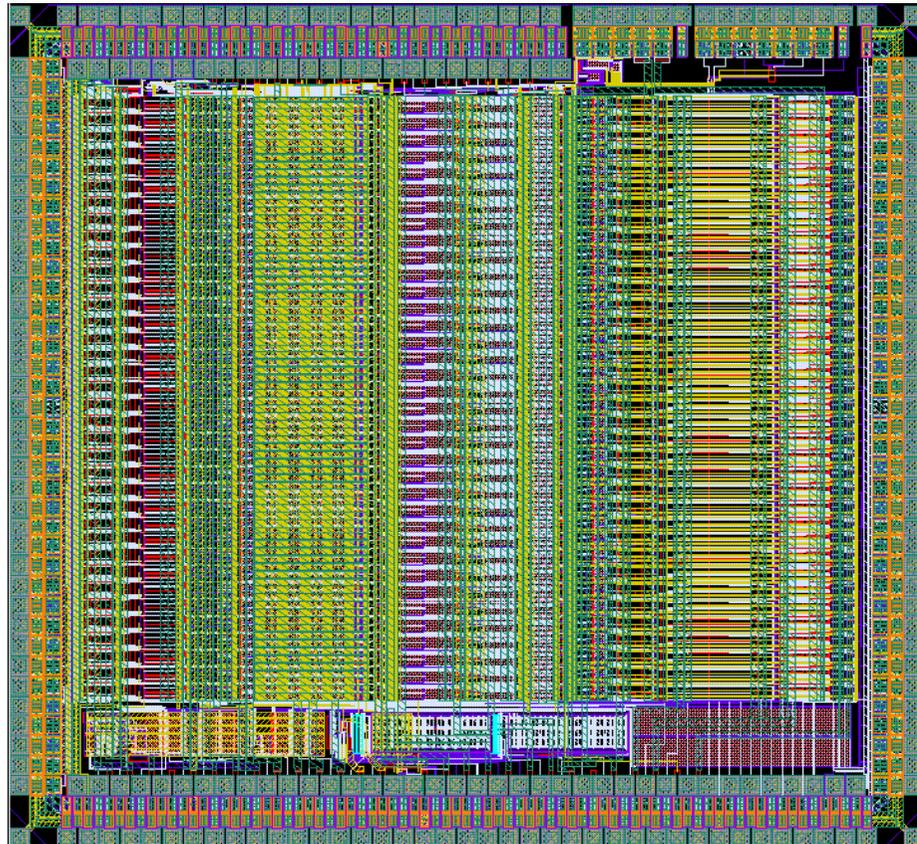
- Common and based on **LCIO, Grid**





SKIROC for W-Si ECAL

- **Silicon Kalorimeter Integrated Read Out Chip (Nov 06)**
 - 36 channels with 16 bits Preamplifier + bi-gain shaper + autotrigger + analog memory + Wilkinson ADC
 - Digital part outside in a FPGA for lack of time and increased flexibility
 - Technology SiGe 0.35 μm AMS. Chip received may 07, tests starting

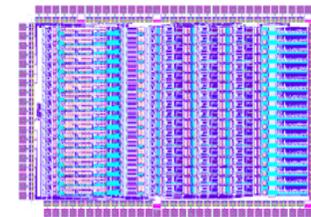
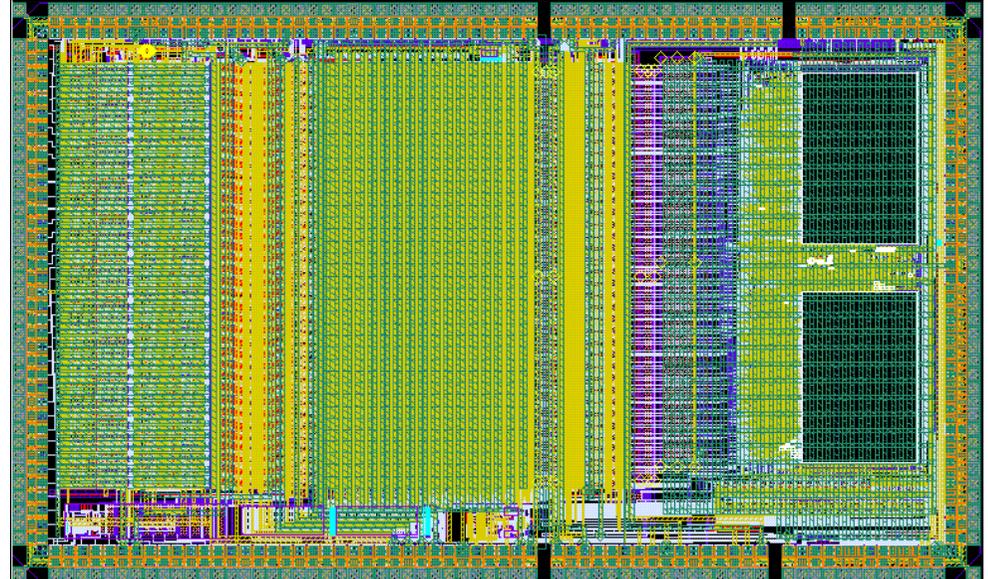


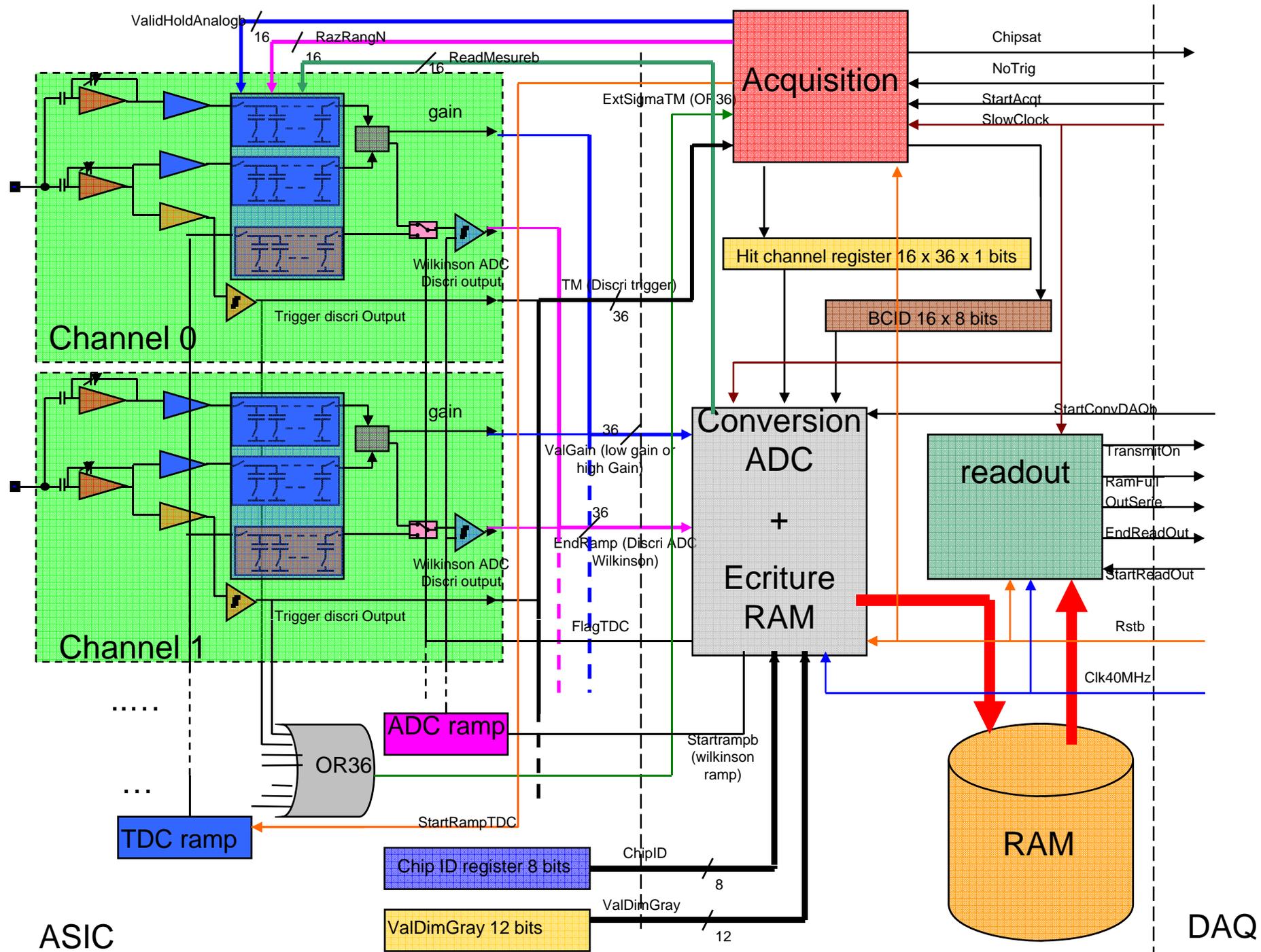


SPIROC overview

JRA3
Milestone

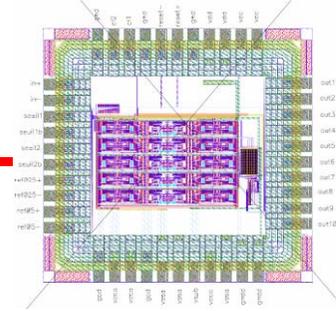
- Silicon Photomultiplier Integrated Read Out Chip
 - A-HCAL read out
- Silicon PM detector
 - $G = 3 \text{ E}5$ to $1 \text{ E}6$
 - Same biasing scheme as TB
- 36 channels
 - Charge measurement (15bits)
 - Time measurement ($< 1\text{ns}$)
- Compatible with old & new DAQ
- **Complex chip**, but many SKIROC, HARDROC, and MAROC features re-used
- **Submitted june 11th**
 - Expected september







On-going R&D : ADCs, FCAL...



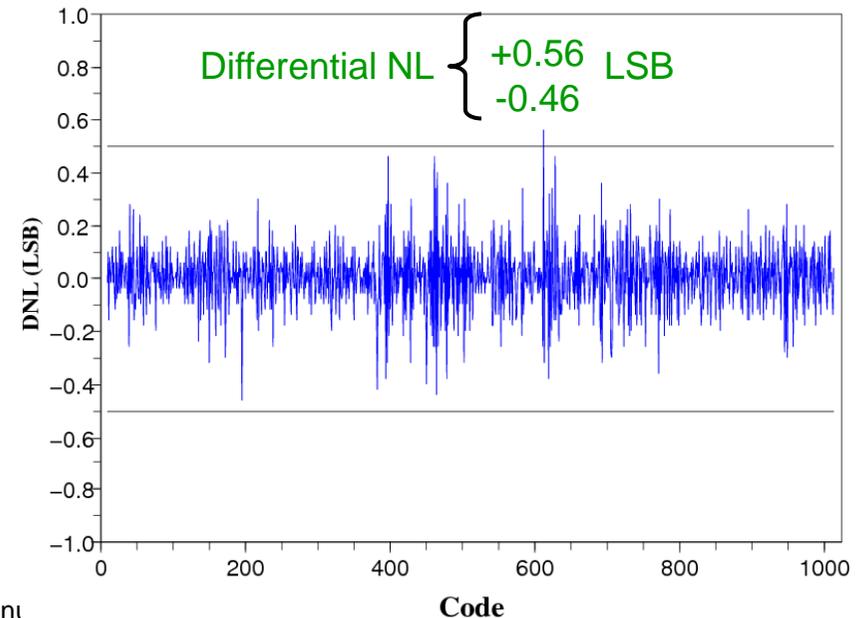
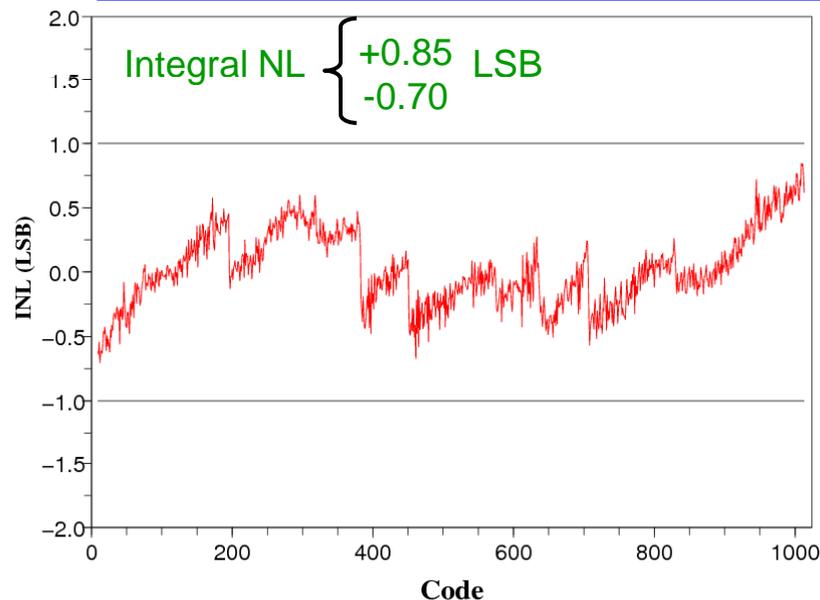
Characteristics:

- Technology: CMOS SiGe 0.35 μ m
- Power supply: 5V (digital: 2.5V)
- Clock frequency: 40 MHz
- Differential architecture
- 10 stages - 1.5 bit/stage
- Die area: 1.2 mm²

Performance (measured):

- Resolution: 10 bits
- Consumption: 35 mW
- Conversion time: 0.25 μ s (@ 40MHz)
- Integrated cons.: (35mW * 0.25 μ s)/200ms= .044 μ W

Noise (measured):
< 0.47 LSB @ 68% C.L.



Common issues

■ Power pulsing studies

- Power management and distribution
- Stability,
- Clock distribution

■ DAQ

- Zero suppressed data
- Minimum number of lines

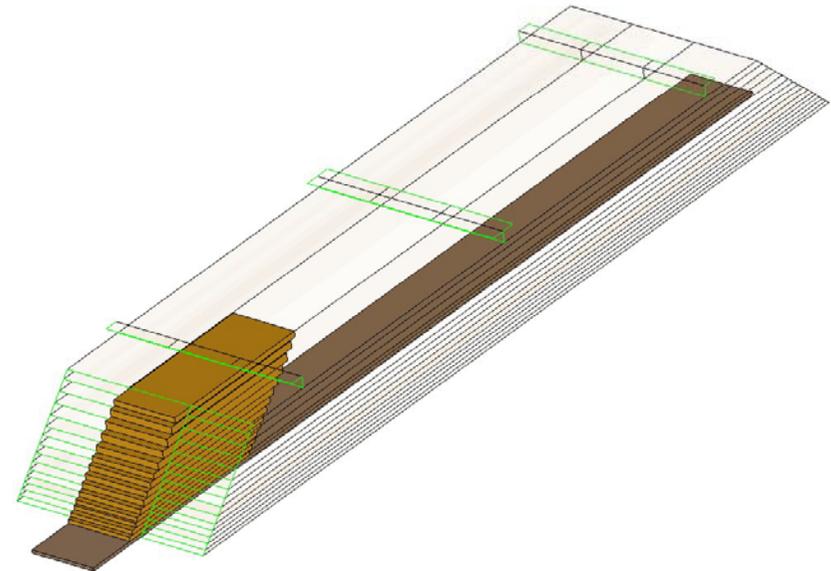
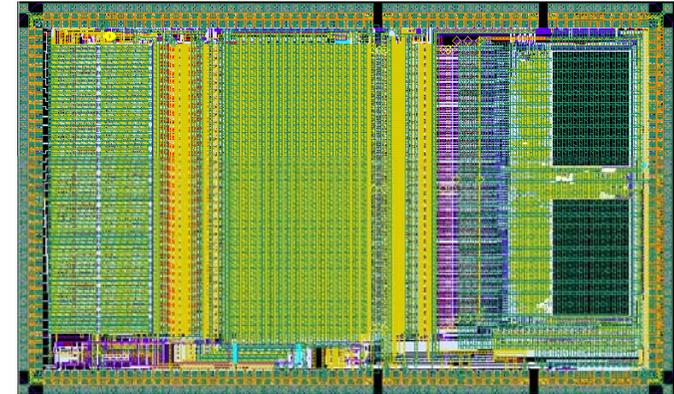
■ ASIC technologies

- « Analog friendly » technologies : now mostly 0.35 μ m AMS SiGe
- Sharing blocks, MPWs : in2p3, Krakow....



Conclusion

- **3 major second generation ASICs for technological prototypes submitted**
 - HARdROC submitted for DHCAL RPCs
 - SKIROC submitted for ECAL Si-W
 - SPIROC for AHCAL SiPM
- **System aspects now proceeding**
 - Power pulsing, Zero-suppress, Auto-trigger, 2nd generation DAQ...
 - On detector boards
 - Connection to DAQ : task force
 - EUDET repository for shared VHDL code
- **EUDET modules in 2009 is challenging !**
 - Production of all ASICs mid 2008 !
 - Organization coming in place



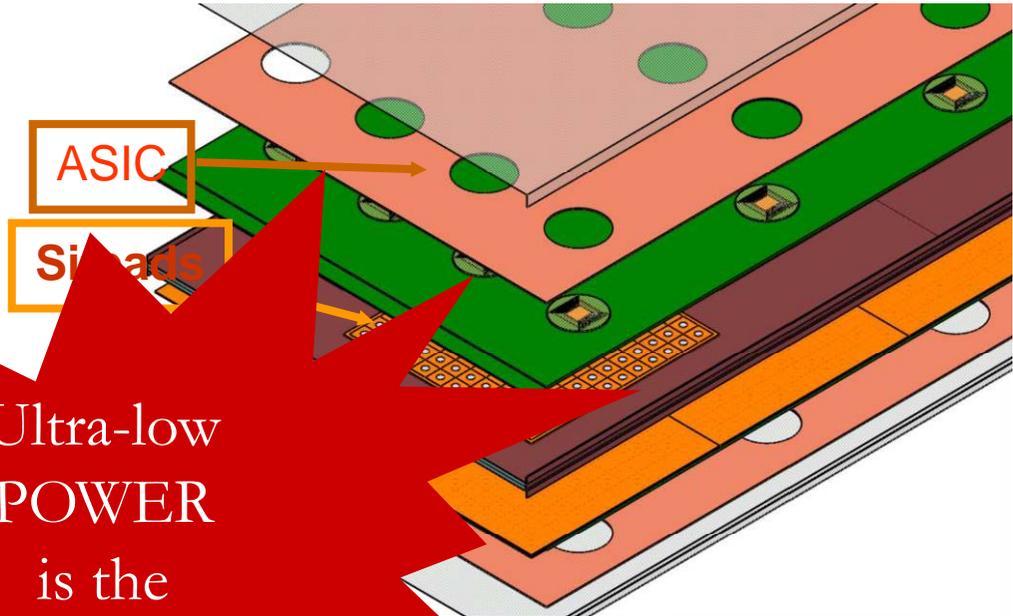
Milestone	Date	Task
Analogue ASIC prototype 1 available	6	E
PCI card prototype available	9	D
AHCAL FE board prototype ready	18	E
Modified stack available	18	B
DHCAL VFE conceptual design ready	18	E
Analogue ASIC prototype 2 available	19	E
Prototype of laser positioning system ready	24	C
Sensor test facility ready	24	C
Readout electronics design ready	24	C
Integrated ASIC available	30	E
Final DAQ system available	30	D
DHCAL VFE engineering design ready	36	E
Front-end electronics infrastructure available	36	E
AHCAL FE boards produced	39	E
Integrated system available	42	B
Detector test facility ready	48	C
Construction complete	48	A

■ Requirements for electronics

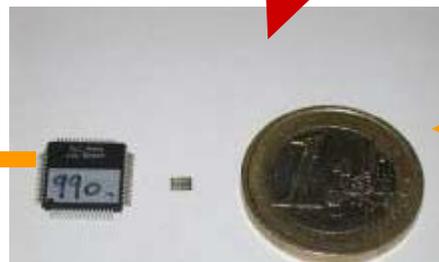
- Large dynamic range (15 bits)
- Auto-trigger on $\frac{1}{2}$ MIP
- On chip zero suppress
- Front-end embedded in detector
- **Ultra-low power** : ($\ll 100$)
- 10^8 channels
- Compactness

■ « Tracker electronics with performance »

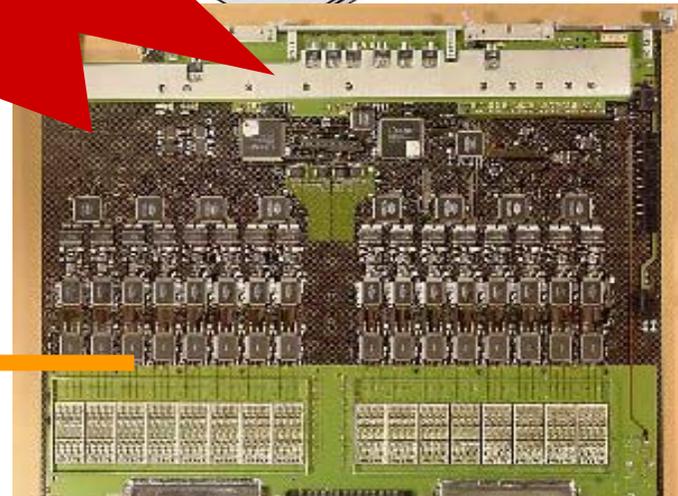
Ultra-low
POWER
is the
KEY issue



ILC : 100 μ W/ch



FLC_PHY3 18ch 10*10mm 5mW/ch



ATLAS LAr FEB 128ch 400*500mm 1 W/ch